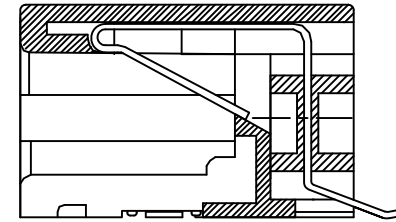
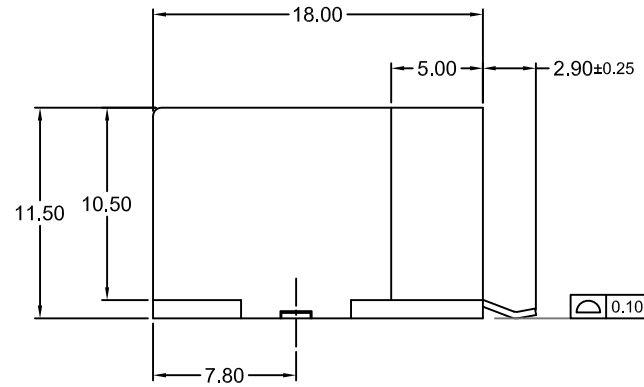
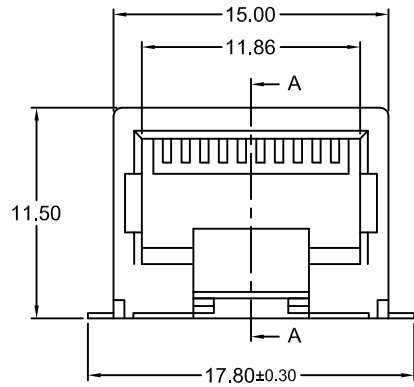
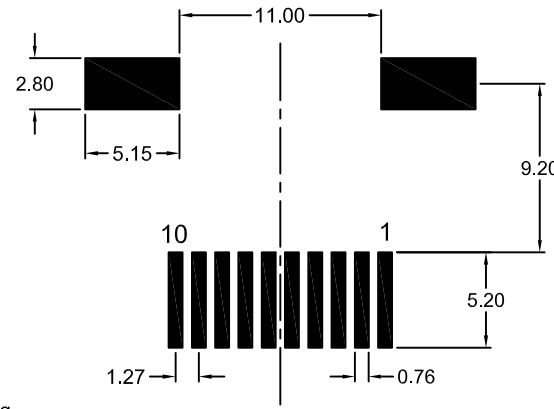
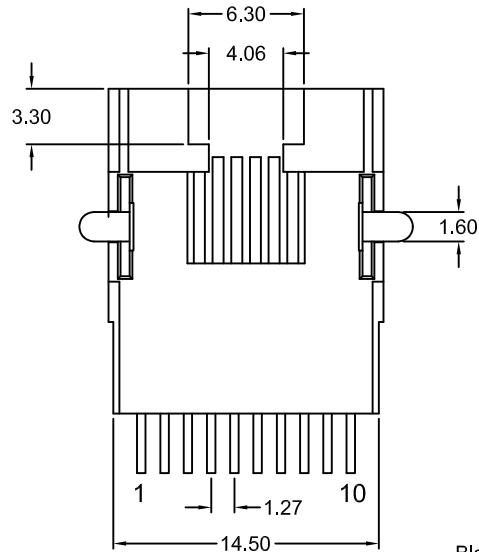


REV.	DESCRIPTION	DATE	DRAWN
A	NEW	28.11.2013	Ronny



A-A



Recommended PCB SMT Layout
(PCB TOLERANCE ±0.05)

Blank: Tray packing
/R = Reel packing

PART NUMBER	GOLD PLATING CONTACT AREA
MJS-100-WD3S1-56/R	6μ"
MJS-100-WD3S1-57/R	15μ"
MJS-100-WD3S1-58/R	30μ"
MJS-100-WD3S1-5H/R	50μ"

Specifications

Current rating: 1.5A
 Insulation resistance: 500MΩ min. / 500V DC
 Withstanding voltage: 1000V rms 60Hz / Minute
 Contact resistance: 40mΩ max. / 20mV DC

Materials

Contact: Phosphor Bronze t=0.35mm
 Plating: Au flash in solder area
 Insulator: PA9T UL 94V-0 (Black)

Operating temperature: -40°C to +105°C
 Processing temperature: +250°C +0/-5°C
 for 10 seconds

Cavity confirms to FCC Rules and
 Registration PAR68, Subparts F.



UNIT mm	GENERAL TOLERANCE		DRAWN Ryan	DATE 28.11.2013	DWG. NO. 1711602	SHEET 1/1
	SCALE Free	X.° ±	.X ±	CHECK Ronny	DATE 28.11.2013	REV. A
		XX. ±	.XX ± 0.13	APPROVE Hogi	DATE 28.11.2013	
		Ang. ± 0° 30'	.XXX ± 0.05			

SMT PCB JACK SIDE ENTRY
 RJ50 <10P10C> non shielded
 wing solder tabs